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PATENT

THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:  
JOYCE S. OEY HEWETT  
ALEXANDER J. PASADYN

Examiner: Lynette T. Umez Eronini

Group Art Unit: 1765

Att'y Docket: 2000.089100/TT4642

Customer No.: 23720

Serial No.: 09/909,112

Filed: July 19, 2001

For: USE OF SLURRY WASTE  
COMPOSITION TO DETERMINE THE  
AMOUNT OF METAL REMOVED  
DURING CHEMICAL MECHANICAL  
POLISHING, AND SYSTEM FOR  
ACCOMPLISHING SAME

RECEIVED  
OCT 20 2003  
TC 1700

RESPONSE TO OFFICE ACTION DATED JULY 8, 2003

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

CERTIFICATE OF MAILING 37 C.F.R. 1.8	
I hereby certify that this correspondence is being deposited with the U.S. Postal Service with sufficient postage as First Class Mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on the date below:	
October 6, 2003 Date	<i>Mary Paul</i> Signature

This paper is submitted in response to the Office Action dated July 8, 2003, for which the three-month date for response is October 8, 2003.

A fee in the amount of \$90.00 is believed to be due in connection with the present paper.

The Director is authorized to deduct such fee, and any other fees required under 37 C.F.R.

§§ 1.16 to 1.21, from Advanced Micro Devices, Inc. Deposit Account No. 01-0365/TT4642.

In the event the monies in that account are insufficient, the Director is authorized to withdraw funds from Williams, Morgan & Amerson, P.C. Deposit Account No. 50-0786/2000.089100.

Reconsideration of the application in view of the following amendments and remarks is respectfully requested.

10/17/2003 AHONDAF1 00000062 010365 09909112  
01 FC:1202 90.00 BA

Material that is abraded  
of a slurry during CMP process as  
material is abraded from the surface  
of a layer being polished. As metal is  
being abraded/polished, the amount of abrasive  
metal in the slurry is measured by  
change in electrode po